

MATERIAL DECLARATION SHEET



Package Type	CD143A-SR70						
Product Line	Semiconductor Products						
Compliance Date	Sept 09, 2025						
RoHS Compliant	Yes	Terminal	e3	MSL	1		

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Encapsulation	Epoxy Resin	0.00544	Amorphous Silica	60676-86-0	91.690	54.332	59.259
				Epoxy Resin A	Proprietary	4.170	2.470	
				Epoxy Resin B	29690-82-2	1.410	0.838	
				Phenol Resin	Proprietary	2.150	1.273	
				Carbon Black	1333-86-4	0.580	0.346	
2	Leadframe	Copper Alloy	0.00272	Copper	7440-50-8	97.780	28.973	29.630
				Iron	7439-89-6	2.118	0.627	
				Phosphorus	7723-14-0	0.023	0.007	
				Zinc	7440-66-6	0.079	0.023	
		Silver Plating	0.00004	Silver	7440-22-4	100.000	0.436	0.436
3	Chip	Silicon	0.00048	Silicon	7440-21-3	91.520	4.762	5.229
				Nickel	7440-02-0	6.080	0.319	
				Aluminum	7429-90-5	2.020	0.128	
				Gold	7440-57-5	0.380	0.020	
4.	Die Attach	Silver Epoxy	0.00010	Silver	7440-22-4	95.190	1.0377	1.089
				Bisphenol-F-(Epichlorhydrin); Epoxy resin	9003-36-5	2.756	0.0294	
				1,4-Bis(2,3-epoxypropoxy) butane	2425-79-8	1.061	0.0113	
				Aromatic polyamine	Proprietary	0.965	0.0103	
				Adipic Acid	124-04-9	0.028	0.0003	
5	Bond Wires	Gold	0.00008	Gold	7440-57-5	99.990	0.8709	0.871
				Non- Au elements	Proprietary	0.010	0.0001	
6	Lead Finish	Matte Tin	0.00032	Tin	7440-31-5	100.000	3.486	3.486
		Total Weight	0.00918					

Important remarks:

1. It is responsibility of the user to verify they are accessing the latest version.